Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

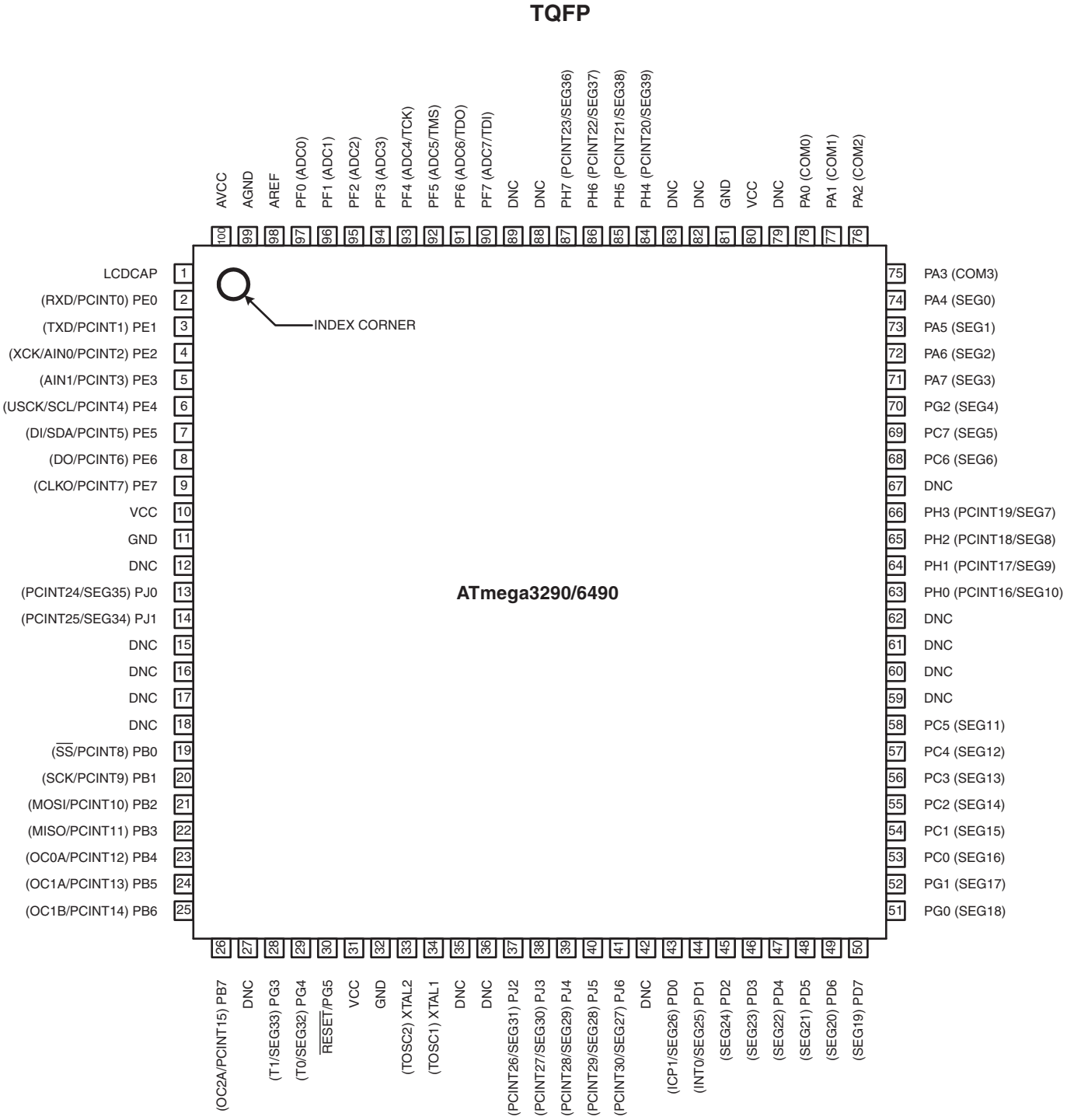
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	AVR
Core Size	8-Bit
Speed	16MHz
Connectivity	SPI, UART/USART, USI
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	53
Program Memory Size	64KB (32K x 16)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atmega649-16au

1. Pin Configurations

Figure 1-1. Pinout ATmega3290/6490



The Atmel® AVR® core combines a rich instruction set with 32 general purpose working registers. All the 32 registers are directly connected to the Arithmetic Logic Unit (ALU), allowing two independent registers to be accessed in one single instruction executed in one clock cycle. The resulting architecture is more code efficient while achieving throughputs up to ten times faster than conventional CISC microcontrollers.

The Atmel ATmega329/3290/649/6490 provides the following features: 32/64K bytes of In-System Programmable Flash with Read-While-Write capabilities, 1/2K bytes EEPROM, 2/4K byte SRAM, 54/69 general purpose I/O lines, 32 general purpose working registers, a JTAG interface for Boundary-scan, On-chip Debugging support and programming, a complete On-chip LCD controller with internal contrast control, three flexible Timer/Counters with compare modes, internal and external interrupts, a serial programmable USART, Universal Serial Interface with Start Condition Detector, an 8-channel, 10-bit ADC, a programmable Watchdog Timer with internal Oscillator, an SPI serial port, and five software selectable power saving modes. The Idle mode stops the CPU while allowing the SRAM, Timer/Counters, SPI port, and interrupt system to continue functioning. The Power-down mode saves the register contents but freezes the Oscillator, disabling all other chip functions until the next interrupt or hardware reset. In Power-save mode, the asynchronous timer and the LCD controller continues to run, allowing the user to maintain a timer base and operate the LCD display while the rest of the device is sleeping. The ADC Noise Reduction mode stops the CPU and all I/O modules except asynchronous timer, LCD controller and ADC, to minimize switching noise during ADC conversions. In Standby mode, the crystal/resonator Oscillator is running while the rest of the device is sleeping. This allows very fast start-up combined with low-power consumption.

The device is manufactured using Atmel's high density non-volatile memory technology. The On-chip In-System re-Programmable (ISP) Flash allows the program memory to be reprogrammed In-System through an SPI serial interface, by a conventional non-volatile memory programmer, or by an On-chip Boot program running on the AVR core. The Boot program can use any interface to download the application program in the Application Flash memory. Software in the Boot Flash section will continue to run while the Application Flash section is updated, providing true Read-While-Write operation. By combining an 8-bit RISC CPU with In-System Self-Programmable Flash on a monolithic chip, the Atmel ATmega329/3290/649/6490 is a powerful microcontroller that provides a highly flexible and cost effective solution to many embedded control applications.

The Atmel ATmega329/3290/649/6490 is supported with a full suite of program and system development tools including: C Compilers, Macro Assemblers, Program Debugger/Simulators, In-Circuit Emulators, and Evaluation kits.

2.2 Comparison between ATmega329, ATmega3290, ATmega649 and ATmega6490

The ATmega329, ATmega3290, ATmega649, and ATmega6490 differs only in memory sizes, pin count and pinout. Table 2-1 on page 6 summarizes the different configurations for the four devices.

Table 2-1. Configuration Summary

Device	Flash	EEPROM	RAM	LCD Segments	General Purpose I/O Pins
ATmega329	32Kbytes	1Kbytes	2Kbytes	4 x 25	54
ATmega3290	32Kbytes	1K bytes	2Kbytes	4 x 40	69
ATmega649	64Kbytes	2Kbytes	4Kbytes	4 x 25	54
ATmega6490	64Kbytes	2Kbytes	4Kbytes	4 x 40	69

2.3 Pin Descriptions

The following section describes the I/O-pin special functions.

2.3.1 V_{CC}

Digital supply voltage.

2.3.2 GND

Ground.

2.3.3 Port A (PA7..PA0)

Port A is an 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port A output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port A pins that are externally pulled low will source current if the pull-up resistors are activated. The Port A pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port A also serves the functions of various special features of the ATmega329/3290/649/6490 as listed on page 67.

2.3.4 Port B (PB7..PB0)

Port B is an 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port B output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port B pins that are externally pulled low will source current if the pull-up resistors are activated. The Port B pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port B has better driving capabilities than the other ports.

Port B also serves the functions of various special features of the ATmega329/3290/649/6490 as listed on page 68.

2.3.5 Port C (PC7..PC0)

Port C is an 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port C output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port C pins that are externally pulled low will source current if the pull-up resistors are activated. The Port C pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port C also serves the functions of special features of the ATmega329/3290/649/6490 as listed on page 71.

2.3.6 Port D (PD7..PD0)

Port D is an 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port D output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port D pins that are externally pulled low will source current if the pull-up resistors are activated. The Port D pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port D also serves the functions of various special features of the ATmega329/3290/649/6490 as listed on page 73.

2.3.7 Port E (PE7..PE0)

Port E is an 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port E output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port E pins that are externally pulled low will source current if the pull-up resistors are activated. The Port E pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port E also serves the functions of various special features of the ATmega329/3290/649/6490 as listed on page 75.

2.3.8 Port F (PF7..PF0)

Port F serves as the analog inputs to the A/D Converter.

Port F also serves as an 8-bit bi-directional I/O port, if the A/D Converter is not used. Port pins can provide internal pull-up resistors (selected for each bit). The Port F output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port F pins that are externally pulled low will source current if the pull-up resistors are activated. The Port F pins are tri-stated when a reset condition becomes active, even if the clock is not running. If the JTAG interface is enabled, the pull-up resistors on pins PF7(TDI), PF5(TMS), and PF4(TCK) will be activated even if a reset occurs.

Port F also serves the functions of the JTAG interface.

2.3.9 Port G (PG5..PG0)

Port G is a 6-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port G output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port G pins that are externally pulled low will source current if the pull-up resistors are activated. The Port G pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port G also serves the functions of various special features of the ATmega329/3290/649/6490 as listed on page 75.

2.3.10 Port H (PH7..PH0)

Port H is a 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port H output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port H pins that are externally pulled low will source current if the pull-up resistors are activated. The Port H pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port H also serves the functions of various special features of the ATmega3290/6490 as listed on page 75.

2.3.11 Port J (PJ6..PJ0)

Port J is a 7-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port J output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port J pins that are externally pulled low will source current if the pull-up resistors are activated. The Port J pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port J also serves the functions of various special features of the ATmega3290/6490 as listed on page 75.

2.3.12 $\overline{\text{RESET}}$

Reset input. A low level on this pin for longer than the minimum pulse length will generate a reset, even if the clock is not running. The minimum pulse length is given in "System and Reset Characteristics" on page 330. Shorter pulses are not guaranteed to generate a reset.

2.3.13 XTAL1

Input to the inverting Oscillator amplifier and input to the internal clock operating circuit.

2.3.14 XTAL2

Output from the inverting Oscillator amplifier.

2.3.15 AVCC

AVCC is the supply voltage pin for Port F and the A/D Converter. It should be externally connected to V_{CC}, even if the ADC is not used. If the ADC is used, it should be connected to V_{CC} through a low-pass filter.

2.3.16 AREF

This is the analog reference pin for the A/D Converter.

2.3.17 LCDCAP

An external capacitor (typical > 470nF) must be connected to the LCDCAP pin as shown in Figure 23-2. This capacitor acts as a reservoir for LCD power (V_{LCD}). A large capacitance reduces ripple on V_{LCD} but increases the time until V_{LCD} reaches its target value.

3. Resources

A comprehensive set of development tools, application notes and datasheets are available for download on http://www.atmel.com/avr.

4. Data Retention

Reliability Qualification results show that the projected data retention failure rate is much less than 1 PPM over 20 years at 85°C or 100 years at 25°C.

5. About Code Examples

This documentation contains simple code examples that briefly show how to use various parts of the device. These code examples assume that the part specific header file is included before compilation. Be aware that not all C compiler vendors include bit definitions in the header files and interrupt handling in C is compiler dependent. Please confirm with the C compiler documentation for more details.

For I/O Registers located in extended I/O map, “IN”, “OUT”, “SBIS”, “SBIC”, “CBI”, and “SBI” instructions must be replaced with instructions that allow access to extended I/O. Typically “LDS” and “STS” combined with “SBRS”, “SBRC”, “SBR”, and “CBR”.

Mnemonics	Operands	Description	Operation	Flags	#Clocks
BRTC	k	Branch if T Flag Cleared	if (T = 0) then PC ← PC + k + 1	None	1/2
BRVS	k	Branch if Overflow Flag is Set	if (V = 1) then PC ← PC + k + 1	None	1/2
BRVC	k	Branch if Overflow Flag is Cleared	if (V = 0) then PC ← PC + k + 1	None	1/2
BRIE	k	Branch if Interrupt Enabled	if (I = 1) then PC ← PC + k + 1	None	1/2
BRID	k	Branch if Interrupt Disabled	if (I = 0) then PC ← PC + k + 1	None	1/2
BIT AND BIT-TEST INSTRUCTIONS					
SBI	P,b	Set Bit in I/O Register	I/O(P,b) ← 1	None	2
CBI	P,b	Clear Bit in I/O Register	I/O(P,b) ← 0	None	2
LSL	Rd	Logical Shift Left	Rd(n+1) ← Rd(n), Rd(0) ← 0	Z,C,N,V	1
LSR	Rd	Logical Shift Right	Rd(n) ← Rd(n+1), Rd(7) ← 0	Z,C,N,V	1
ROL	Rd	Rotate Left Through Carry	Rd(0)←C,Rd(n+1)← Rd(n),C←Rd(7)	Z,C,N,V	1
ROR	Rd	Rotate Right Through Carry	Rd(7)←C,Rd(n)← Rd(n+1),C←Rd(0)	Z,C,N,V	1
ASR	Rd	Arithmetic Shift Right	Rd(n) ← Rd(n+1), n=0..6	Z,C,N,V	1
SWAP	Rd	Swap Nibbles	Rd(3..0)←Rd(7..4),Rd(7..4)←Rd(3..0)	None	1
BSET	s	Flag Set	SREG(s) ← 1	SREG(s)	1
BCLR	s	Flag Clear	SREG(s) ← 0	SREG(s)	1
BST	Rr, b	Bit Store from Register to T	T ← Rr(b)	T	1
BLD	Rd, b	Bit load from T to Register	Rd(b) ← T	None	1
SEC		Set Carry	C ← 1	C	1
CLC		Clear Carry	C ← 0	C	1
SEN		Set Negative Flag	N ← 1	N	1
CLN		Clear Negative Flag	N ← 0	N	1
SEZ		Set Zero Flag	Z ← 1	Z	1
CLZ		Clear Zero Flag	Z ← 0	Z	1
SEI		Global Interrupt Enable	I ← 1	I	1
CLI		Global Interrupt Disable	I ← 0	I	1
SES		Set Signed Test Flag	S ← 1	S	1
CLS		Clear Signed Test Flag	S ← 0	S	1
SEV		Set Twos Complement Overflow.	V ← 1	V	1
CLV		Clear Twos Complement Overflow	V ← 0	V	1
SET		Set T in SREG	T ← 1	T	1
CLT		Clear T in SREG	T ← 0	T	1
SEH		Set Half Carry Flag in SREG	H ← 1	H	1
CLH		Clear Half Carry Flag in SREG	H ← 0	H	1
DATA TRANSFER INSTRUCTIONS					
MOV	Rd, Rr	Move Between Registers	Rd ← Rr	None	1
MOVW	Rd, Rr	Copy Register Word	Rd+1:Rd ← Rr+1:Rr	None	1
LDI	Rd, K	Load Immediate	Rd ← K	None	1
LD	Rd, X	Load Indirect	Rd ← (X)	None	2
LD	Rd, X+	Load Indirect and Post-Inc.	Rd ← (X), X ← X + 1	None	2
LD	Rd, - X	Load Indirect and Pre-Dec.	X ← X - 1, Rd ← (X)	None	2
LD	Rd, Y	Load Indirect	Rd ← (Y)	None	2
LD	Rd, Y+	Load Indirect and Post-Inc.	Rd ← (Y), Y ← Y + 1	None	2
LD	Rd, - Y	Load Indirect and Pre-Dec.	Y ← Y - 1, Rd ← (Y)	None	2
LDD	Rd,Y+q	Load Indirect with Displacement	Rd ← (Y + q)	None	2
LD	Rd, Z	Load Indirect	Rd ← (Z)	None	2
LD	Rd, Z+	Load Indirect and Post-Inc.	Rd ← (Z), Z ← Z+1	None	2
LD	Rd, -Z	Load Indirect and Pre-Dec.	Z ← Z - 1, Rd ← (Z)	None	2
LDD	Rd, Z+q	Load Indirect with Displacement	Rd ← (Z + q)	None	2
LDS	Rd, k	Load Direct from SRAM	Rd ← (k)	None	2
ST	X, Rr	Store Indirect	(X) ← Rr	None	2
ST	X+, Rr	Store Indirect and Post-Inc.	(X) ← Rr, X ← X + 1	None	2
ST	- X, Rr	Store Indirect and Pre-Dec.	X ← X - 1, (X) ← Rr	None	2
ST	Y, Rr	Store Indirect	(Y) ← Rr	None	2
ST	Y+, Rr	Store Indirect and Post-Inc.	(Y) ← Rr, Y ← Y + 1	None	2
ST	- Y, Rr	Store Indirect and Pre-Dec.	Y ← Y - 1, (Y) ← Rr	None	2
STD	Y+q,Rr	Store Indirect with Displacement	(Y + q) ← Rr	None	2
ST	Z, Rr	Store Indirect	(Z) ← Rr	None	2
ST	Z+, Rr	Store Indirect and Post-Inc.	(Z) ← Rr, Z ← Z + 1	None	2
ST	-Z, Rr	Store Indirect and Pre-Dec.	Z ← Z - 1, (Z) ← Rr	None	2
STD	Z+q,Rr	Store Indirect with Displacement	(Z + q) ← Rr	None	2
STS	k, Rr	Store Direct to SRAM	(k) ← Rr	None	2
LPM		Load Program Memory	R0 ← (Z)	None	3
LPM	Rd, Z	Load Program Memory	Rd ← (Z)	None	3
LPM	Rd, Z+	Load Program Memory and Post-Inc	Rd ← (Z), Z ← Z+1	None	3
SPM		Store Program Memory	(Z) ← R1:R0	None	-

Mnemonics	Operands	Description	Operation	Flags	#Clocks
IN	Rd, P	In Port	Rd ← P	None	1
OUT	P, Rr	Out Port	P ← Rr	None	1
PUSH	Rr	Push Register on Stack	STACK ← Rr	None	2
POP	Rd	Pop Register from Stack	Rd ← STACK	None	2
MCU CONTROL INSTRUCTIONS					
NOP		No Operation		None	1
SLEEP		Sleep	(see specific descr. for Sleep function)	None	1
WDR		Watchdog Reset	(see specific descr. for WDR/timer)	None	1
BREAK		Break	For On-chip Debug Only	None	N/A

8. Ordering Information

8.1 ATmega329

Speed (MHz)[3]	Power Supply	Ordering Code[2]	Package Type[1]	Operational Range
8	1.8 - 5.5V	ATmega329V-8AU ATmega329V-8AUR[4] ATmega329V-8MU ATmega329V-8MUR[4]	64A 64A 64M1 64M1	Industrial (-40°C to 85°C)
16	2.7 - 5.5V	ATmega329-16AU ATmega329-16AUR[4] ATmega329-16MU ATmega329-16MUR[4]	64A 64A 64M1 64M1	Industrial (-40°C to 85°C)

Notes:
1. This device can also be supplied in wafer form. Please contact your local Atmel sales office for detailed ordering information and minimum quantities.
2. Pb-free packaging alternative, complies to the European Directive for Restriction of Hazardous Substances (RoHS directive). Also Halide free and fully Green.
3. For Speed vs. V_{CC} see Figure 28-1 on page 328 and Figure 28-2 on page 328.
4. Tape & Reel

Package Type	
64A	64-lead, 14 x 14 x 1.0 mm, Thin Profile Plastic Quad Flat Package (TQFP)
64M1	64-pad, 9 x 9 x 1.0 mm, Quad Flat No-Lead/Micro Lead Frame Package (QFN/MLF)
100A	100-lead, 14 x 14 x 1.0 mm, 0.5 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)

8.2 ATmega3290

Speed (MHz)[3]	Power Supply	Ordering Code[2]	Package Type[1]	Operational Range
8	1.8 - 5.5V	ATmega3290V-8AU ATmega3290V-8AUR[4]	100A 100A	Industrial (-40°C to 85°C)
16	2.7 - 5.5V	ATmega3290-16AU ATmega3290-16AUR[4]	100A 100A	Industrial (-40°C to 85°C)

Notes:
1. This device can also be supplied in wafer form. Please contact your local Atmel sales office for detailed ordering information and minimum quantities.
2. Pb-free packaging alternative, complies to the European Directive for Restriction of Hazardous Substances (RoHS directive). Also Halide free and fully Green.
3. For Speed vs. V_{CC} see Figure 28-1 on page 328 and Figure 28-2 on page 328.
4. Tape & Reel

Package Type	
64A	64-lead, 14 x 14 x 1.0 mm, Thin Profile Plastic Quad Flat Package (TQFP)
64M1	64-pad, 9 x 9 x 1.0 mm, Quad Flat No-Lead/Micro Lead Frame Package (QFN/MLF)
100A	100-lead, 14 x 14 x 1.0 mm, 0.5 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)

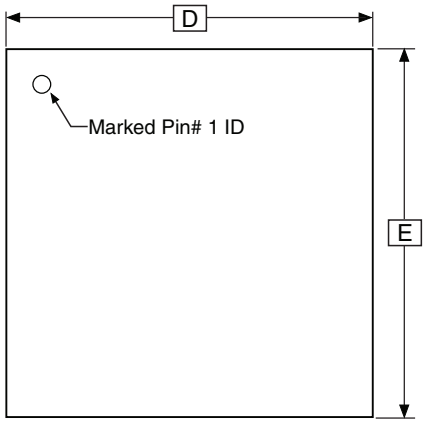
8.3 ATmega649

Speed (MHz)[3]	Power Supply	Ordering Code[2]	Package Type[1]	Operational Range
8	1.8 - 5.5V	ATmega649V-8AU ATmega649V-8AUR[4] ATmega649V-8MU ATmega649V-8MUR[4]	64A 64A 64M1 64M1	Industrial (-40°C to 85°C)
16	2.7 - 5.5V	ATmega649-16AU ATmega649-16AUR[4] ATmega649-16MU ATmega649-16MUR[4]	64A 64A 64M1 64M1	Industrial (-40°C to 85°C)

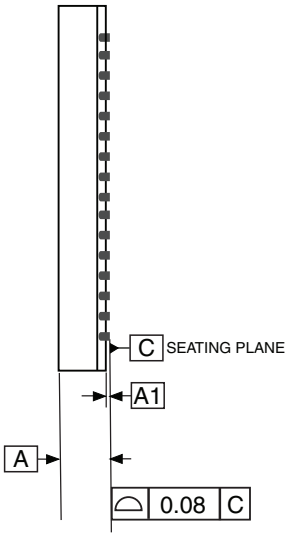
Notes:
1. This device can also be supplied in wafer form. Please contact your local Atmel sales office for detailed ordering information and minimum quantities.
2. Pb-free packaging alternative, complies to the European Directive for Restriction of Hazardous Substances (RoHS directive). Also Halide free and fully Green.
3. For Speed vs. V_{CC} see Figure 28-1 on page 328 and Figure 28-2 on page 328.
4. Tape & Reel

Package Type	
64A	64-lead, 14 x 14 x 1.0 mm, Thin Profile Plastic Quad Flat Package (TQFP)
64M1	64-pad, 9 x 9 x 1.0 mm, Quad Flat No-Lead/Micro Lead Frame Package (QFN/MLF)
100A	100-lead, 14 x 14 x 1.0 mm, 0.5 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)

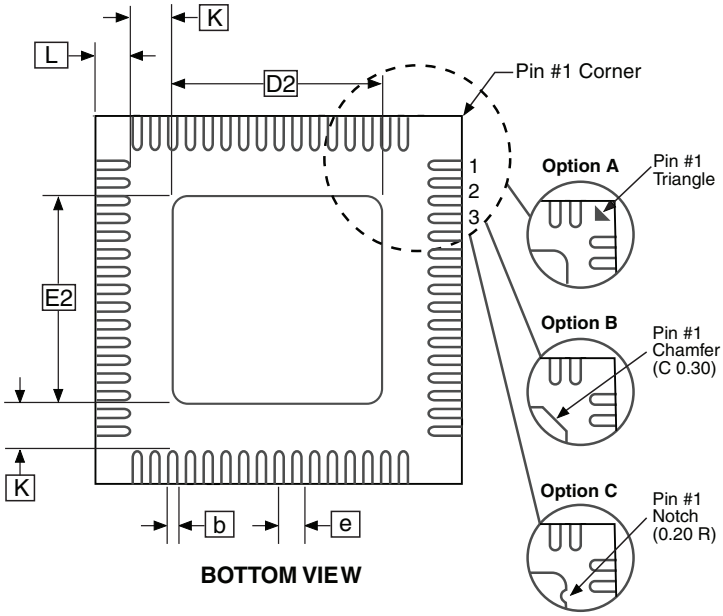
9.2 64M1



TOP VIEW



SIDE VIEW



BOTTOM VIEW

COMMON DIMENSIONS
(Unit of Measure = mm)

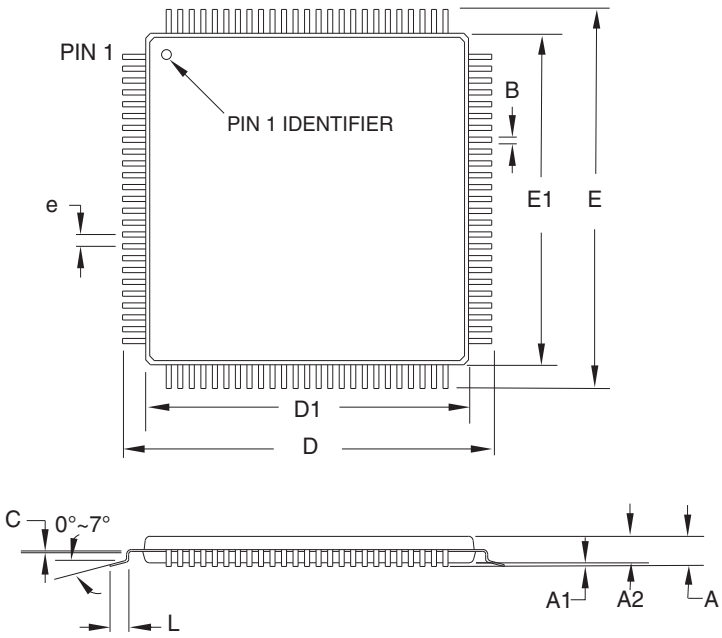
SYMBOL	MIN	NOM	MAX	NOTE
A	0.80	0.90	1.00	
A1	–	0.02	0.05	
b	0.18	0.25	0.30	
D	8.90	9.00	9.10	
D2	5.20	5.40	5.60	
E	8.90	9.00	9.10	
E2	5.20	5.40	5.60	
e		0.50 BSC		
L	0.35	0.40	0.45	
K	1.25	1.40	1.55	

Notes:
1. JEDEC Standard MO-220, (SAW Singulation) Fig. 1, VMMD.
2. Dimension and tolerance conform to ASMEY14.5M-1994.

2010-10-19

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**64M1**, 64-pad, 9 x 9 x 1.0 mm Body, Lead Pitch 0.50 mm, 5.40 mm Exposed Pad, Micro Lead Frame Package (MLF)	64M1	H

9.3 100A



COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	1.20	
A1	0.05	–	0.15	
A2	0.95	1.00	1.05	
D	15.75	16.00	16.25	
D1	13.90	14.00	14.10	Note 2
E	15.75	16.00	16.25	
E1	13.90	14.00	14.10	Note 2
B	0.17	–	0.27	
C	0.09	–	0.20	
L	0.45	–	0.75	
e	0.50 TYP			

Notes:
1. This package conforms to JEDEC reference MS-026, Variation AED.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25 mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.08 mm maximum.

2010-10-20

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**100A,** 100-lead, 14 x 14 mm Body Size, 1.0 mm Body Thickness, 0.5 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)	100A	D

10. Errata

10.1 ATmega329

10.1.1 ATmega329 rev. C

- **Interrupts may be lost when writing the timer registers in the asynchronous timer**

1. **Interrupts may be lost when writing the timer registers in the asynchronous timer**

   The interrupt will be lost if a timer register that is synchronous timer clock is written when the asynchronous Timer/Counter register (TCNTx) is 0x00.

   Problem Fix/Wortkaround

   Always check that the asynchronous Timer/Counter register neither have the value 0xFF nor 0x00 before writing to the asynchronous Timer Control Register (TCCRx), asynchronous Timer Counter Register (TCNTx), or asynchronous Output Compare Register (OCRx).

10.1.2 ATmega329 rev. B

Not sampled.

10.1.3 ATmega329 rev. A

- **LCD contrast voltage too high**
- **Interrupts may be lost when writing the timer registers in the asynchronous timer**

1. **LCD contrast voltage too high**

   When the LCD is active and using low power waveform, the LCD contrast voltage can be too high. This occurs when V_{CC} is higher than V_{LCD}, and when using low LCD drivetime.

   Problem Fix/Workaround

   There are several possible workarounds:

   - Use normal waveform instead of low power waveform

   - Use drivetime of 375 µs or longer

2. **Interrupts may be lost when writing the timer registers in the asynchronous timer**

   The interrupt will be lost if a timer register that is synchronous timer clock is written when the asynchronous Timer/Counter register (TCNTx) is 0x00.

   Problem Fix/Wortkaround

   Always check that the asynchronous Timer/Counter register neither have the value 0xFF nor 0x00 before writing to the asynchronous Timer Control Register (TCCRx), asynchronous Timer Counter Register (TCNTx), or asynchronous Output Compare Register (OCRx).

10.2 ATmega3290

10.2.1 ATmega3290 rev. C

- **Interrupts may be lost when writing the timer registers in the asynchronous timer**

1. **Interrupts may be lost when writing the timer registers in the asynchronous timer**

   The interrupt will be lost if a timer register that is synchronous timer clock is written when the asynchronous Timer/Counter register (TCNTx) is 0x00.

   Problem Fix/Wortkaround

   Always check that the asynchronous Timer/Counter register neither have the value 0xFF nor 0x00 before writing to the asynchronous Timer Control Register (TCCRx), asynchronous Timer Counter Register (TCNTx), or asynchronous Output Compare Register (OCRx).

10.2.2 ATmega3290 rev. B

Not sampled.

10.2.3 ATmega3290 rev. A

- **LCD contrast voltage too high**
- **Interrupts may be lost when writing the timer registers in the asynchronous timer**

1. **LCD contrast voltage too high**

   When the LCD is active and using low power waveform, the LCD contrast voltage can be too high. This occurs when V_{CC} is higher than V_{LCD}, and when using low LCD drivetime.

   Problem Fix/Workaround

   There are several possible workarounds:

   - Use normal waveform instead of low power waveform

   - Use drivetime of 375 µs or longer

2. **Interrupts may be lost when writing the timer registers in the asynchronous timer**

   The interrupt will be lost if a timer register that is synchronous timer clock is written when the asynchronous Timer/Counter register (TCNTx) is 0x00.

   Problem Fix/Wortkaround

   Always check that the asynchronous Timer/Counter register neither have the value 0xFF nor 0x00 before writing to the asynchronous Timer Control Register (TCCRx), asynchronous Timer Counter Register (TCNTx), or asynchronous Output Compare Register (OCRx).

10.3 ATmega649

10.3.1 ATmega649 rev. A

- **Interrupts may be lost when writing the timer registers in the asynchronous timer**

1. **Interrupts may be lost when writing the timer registers in the asynchronous timer**

   The interrupt will be lost if a timer register that is synchronous timer clock is written when the asynchronous Timer/Counter register (TCNTx) is 0x00.

   Problem Fix/Wortkaround

   Always check that the asynchronous Timer/Counter register neither have the value 0xFF nor 0x00 before writing to the asynchronous Timer Control Register (TCCRx), asynchronous Timer Counter Register (TCNTx), or asynchronous Output Compare Register (OCRx).

10.4 ATmega6490

10.4.1 ATmega6490 rev. A

- **Interrupts may be lost when writing the timer registers in the asynchronous timer**

1. **Interrupts may be lost when writing the timer registers in the asynchronous timer**

   The interrupt will be lost if a timer register that is synchronous timer clock is written when the asynchronous Timer/Counter register (TCNTx) is 0x00.

   Problem Fix/Wortkaround

   Always check that the asynchronous Timer/Counter register neither have the value 0xFF nor 0x00 before writing to the asynchronous Timer Control Register (TCCRx), asynchronous Timer Counter Register (TCNTx), or asynchronous Output Compare Register (OCRx).

11. Datasheet Revision History

Please note that the referring page numbers in this section are referring to this document.The referring revision in this section are referring to the document revision.

11.1 Rev. 2552K – 04/11

1. Removed “Preliminary” from the front page.
2. Removed “Disclaimer Section” from the datasheet.
3. Updated Table 28-5 on page 330 “BODLEVEL Fuse Coding(1)” .
4. Updated Table 28-8 on page 334 “LCD Controller Characteristics” .
5. Updated “Ordering Information” on page 372 to include “Tape & Reel” devices. The “AI” and “MI” devices removed.
6. Updated “Errata” on page 379.
7. Updated the datasheet according to the Atmel new brand style guide, including the last page.

11.2 Rev. 2552J – 08/07

1. Updated “Features” on page 1.
2. Added “Data Retention” on page 9.
3. Updated “Serial Programming Algorithm” on page 309.
4. Updated “Speed Grades” on page 328.
5. Updated “System and Reset Characteristics” on page 330.
6. Moved Register Descriptions to the end of each chapter.

11.3 Rev. 2552I – 04/07

1. Updated date in backpage
2. Updated column in Table 28-5 on page 330.

11.4 Rev. 2552H – 11/06

1. **Updated Table 28-7 on page 333.**
2. **Updated note in Table 28-7 on page 333 and Table 28-2 on page 329.**

11.5 Rev. 2552G – 07/06

1. Updated Table 14-2 on page 104, Table 14-4 on page 104, Table 16-3 on page 133, Table 16-5 on page 134, Table 16-5 on page 134, Table 17-2 on page 153 and Table 17-4 on page 154.
2. Updated "Fast PWM Mode" on page 124.
3. Updated Features in "USI – Universal Serial Interface" on page 195.
4. Added "Clock speed considerations." on page 202.
5. "Errata" on page 379.

11.6 Rev. 2552F – 06/06

1. Updated "Calibrated Internal RC Oscillator" on page 29.
2. Updated "OSCCAL – Oscillator Calibration Register" on page 32
3. Added Table 28-2 on page 329.

11.7 Rev. 2552E – 04/06

1. Updated "Calibrated Internal RC Oscillator" on page 29.

11.8 Rev. 2552D – 03/06

1. Updated "Errata" on page 379.

11.9 Rev. 2552C – 03/06

1. Added "Resources" on page 9.
2. Added Addresses in Registers.
3. Updated number of General Purpose I/O pins.
4. Updated code example in "Bit 0 – IVCE: Interrupt Vector Change Enable" on page 53.
5. Updated Introduction in "I/O-Ports" on page 59.
6. Updated "SPI – Serial Peripheral Interface" on page 158.
7. Updated "Bit 6 – ACBG: Analog Comparator Bandgap Select" on page 209.
8. Updated Features in "Analog to Digital Converter" on page 211.
9. Updated "Prescaling and Conversion Timing" on page 214.
10. Updated features in "LCD Controller" on page 228.
11. Updated "ATmega329/3290/649/6490 Boot Loader Parameters" on page 290.
12. Updated "DC Characteristics" on page 310.
13. Updated "" on page 334.

11.10 Rev. 2552B – 05/05

1. MLF-package alternative changed to “Quad Flat No-Lead/Micro Lead Frame Package QFN/MLF”.
2. Added “Pin Change Interrupt Timing” on page 54.
3. Updated Table 23-6 on page 242, Table 23-7 on page 243 and Table 27-15 on page 310.
4. Added Figure 27-12 on page 312.
5. Updated Figure 22-9 on page 219 and Figure 27-5 on page 304.
6. Updated algorithm “Enter Programming Mode” on page 299.
7. Added “Supply Current of I/O modules” on page 340.
8. Updated “Ordering Information” on page 372.

11.11 Rev. 2552A –11/04

1. Initial version.

Atmel Corporation
2325 Orchard Parkway
San Jose, CA 95131
USA
Tel: (+1)(408) 441-0311
Fax: (+1)(408) 487-2600
www.atmel.com

Atmel Asia Limited
Unit 1-5 & 16, 19/F
BEA Tower, Millennium City 5
418 Kwun Tong Road
Kwun Tong, Kowloon
HONG KONG
Tel: (+852) 2245-6100
Fax: (+852) 2722-1369

Atmel Munich GmbH
Business Campus
Parkring 4
D-85748 Garching b. Munich
GERMANY
Tel: (+49) 89-31970-0
Fax: (+49) 89-3194621

Atmel Japan
9F, Tonetsu Shinkawa Bldg.
1-24-8 Shinkawa
Chuo-ku, Tokyo 104-0033
JAPAN
Tel: (+81)(3) 3523-3551
Fax: (+81)(3) 3523-7581